20131121000 **PCN Number: PCN Date:** 11/22/2013 Qualification of JCET Chuzhou as Additional Assembly/Test Site for SOT Package Title: **Devices PCN** Manager **Customer Contact: Phone:** +1(214)480-6037 Dept: **Quality Services** Date Provided at **Proposed 1st Ship Date:** 02/22/2014 **Estimated Sample Availability:** Sample request **Change Type: Assembly Site Assembly Process Assembly Materials Electrical Specification** Mechanical Specification Design Test Site Packing/Shipping/Labeling **Test Process** Wafer Bump Site Wafer Bump Material Wafer Bump Process Wafer Fab Materials Wafer Fab Process Wafer Fab Site Part number change **PCN Details**

Description of Change:

Qualification of JCET Chuzhou as Additional Assembly/Test Site for DCY Package Devices. Material differences are shown in the following table:

	NFME	JCET Chuzhou
Mold Compound	SID# R-17	SID# 013101006201

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MO.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Changes to product identification resulting from this PCN:

Assembly Site		
NFME	Assembly Site Origin (22L)	ASO: NS2
JCET Chuzhou	Assembly Site Origin (22L)	ASO: GP6

Sample product shipping label (not actual product label)



5A (L)TO:1750



(1P) SN74LS07NSR (a) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483SI2 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MV6 (2P) REV: 23L) ACO: MYS

ASSEMBLY SITE CODES: NFME = E, JCET Chuzhou = F

Product Affected:			
LM317DCYR	TLV1117-18CDCYRG3	TLV1117CDCYRG3	UA78M05IDCYR
LM317DCYRG3	TLV1117-18IDCYR	TLV1117IDCYR	UA78M05IDCYRG3
LM317MDCYR	TLV1117-18IDCYRG3	TLV1117IDCYRE3	UA78M33CDCYR
LM317MDCYRG3	TLV1117CDCYR	TLV1117IDCYRG3	UA78M33CDCYRG3
SN78MCDCYR	TLV1117CDCYR/2354	UA78M05CDCYR	
TLV1117-18CDCYR	TLV1117CDCYRE3	UA78M05CDCYRG3	

Qualification Data						
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.						
Qual Vehicle 1 : LM317DCYR (MSL2-260C)						
Package Construction Details						
Assembly Site:			Mold Comp	pound: 013101006201		201
# Pins-Designator, Family:	4-DCY, SOT		Mount Comp	ound:	011204001902	
Lead Finish, Base	Matte 9	Matte Sn, Cu Bo		d Wire: 2.0 Mil Dia. Cu		Cu
Qualification:						
Reliability Test	Reliability Test		Conditions		Sample Size / Fail	
,	Hability Test			Lot 1		Lot3
Electrical Characterization		-		30/0		
**Life Test		150C (300 Hrs)		77/0		77/0
**Biased HAST		130C/85%RH (192 Hrs)		77/0	77/0	77/0
**Temp Cycle, -65C/150C		1000 Cycles		77/0	77/0	77/0
**High Temp Storage Bake		170C (600 Hrs)		77/0	77/0	77/0
**Autoclave		121C, 2 atm (192 Hrs)		77/0	77/0	77/0
Salt Atmosphere		24 Hrs		22/0	22/0	22/0
Solderability		Steam age, 8 hours; PB-Free solder		22/0	22/0	22/0
X-ray		(top side only)		5/0	5/0	5/0
Flammability (UL 94V-0)		(UL 94V-0)		5/0	5/0	5/0
Flammability (UL 94V-0)		(UL 94V-0)		5/0	5/0	5/0
Flammability (IEC 695-2-2)		(IEC 695-2-2)		5/0	5/0	5/0
Manufacturability Qualification (MQ) (p		(per mfg. Site specification)		Pass	-	-
Moisture Sensitivity		L2-260C		12/0	12/0	12/0
**- Preconditioning sequence: Level 2-260C.						

Qual Vehicle 2 : TLV1117-18CDCYR (MSL2-260C)						
Package Construction Details						
Assembly Site:	JCET CHUZHOU	Mold Compound:		013101006201		
# Pins-Designator, Family:	4-DCY, SOT	Mount Comp	oound:	011204001902		
Lead Finish, Base	Matte Sn, Cu	Bono	l Wire:	2.0 Mil Dia. Cu		
Qualification: Plan Test Results						
Reliability Test	Conditions	Conditions		Sample Size / Fail		
Reliability Test	Conditions			Lot 2	Lot3	
**Biased HAST 130C/85%RH (1		192 Hrs)	77/0	77/0	77/0	
X-ray (top side only)			5/0	5/0	5/0	
Manufacturability Qualification (M	Q) (per mfg. Site s	(per mfg. Site specification)		-	-	
**- Preconditioning sequence: Level 2-260C.						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com